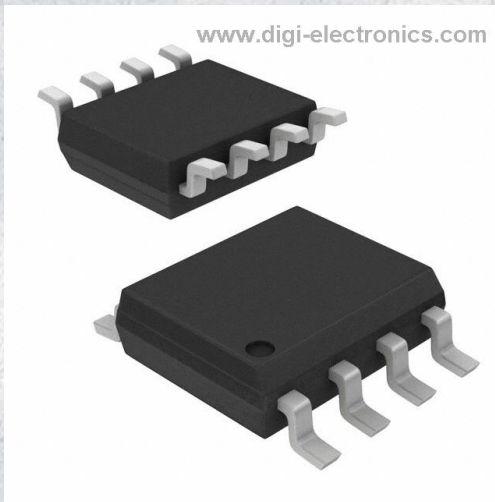


FDS6910 Datasheet



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	FDS6910-DG
Manufacturer	onsemi
Manufacturer Product Number	FDS6910
Description	MOSFET 2N-CH 30V 7.5A 8SOIC
Detailed Description	Mosfet Array 30V 7.5A 900mW Surface Mount 8-SO IC



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

FDS6910

Series:

PowerTrench®

Technology:

MOSFET (Metal Oxide)

FET Feature:

Logic Level Gate

Current - Continuous Drain (Id) @ 25°C:

7.5A

Vgs(th) (Max) @ Id:

3V @ 250µA

Input Capacitance (Ciss) (Max) @ Vds:

1130pF @ 15V

Operating Temperature:

-55°C ~ 150°C (Tj)

Package / Case:

8-SOIC (0.154", 3.90mm Width)

Base Product Number:

FDS69

Manufacturer:

onsemi

Product Status:

Obsolete

Configuration:

2 N-Channel (Dual)

Drain to Source Voltage (Vdss):

30V

Rds On (Max) @ Id, Vgs:

13mOhm @ 7.5A, 10V

Gate Charge (Qg) (Max) @ Vgs:

24nC @ 10V

Power - Max:

900mW

Mounting Type:

Surface Mount

Supplier Device Package:

8-SOIC

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.21.0095

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99

ON Semiconductor

Is Now

The logo for onsemi, featuring the word "onsemi" in a dark teal, lowercase, sans-serif font. The letter "i" is stylized with a white dot and a teal vertical bar. A small orange triangle is positioned above the top right of the "i". A trademark symbol (TM) is located to the right of the logo.

To learn more about onsemi™, please visit our website at
www.onsemi.com

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ON Semiconductor®

FDS6910

Dual N-Channel Logic Level PowerTrench® MOSFET

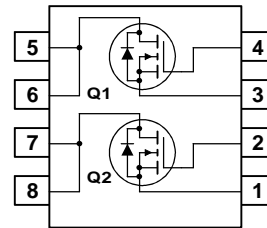
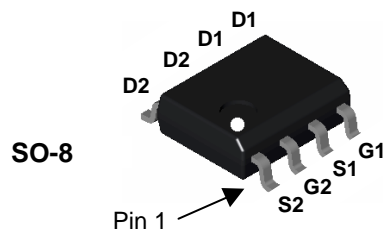
General Description

These N-Channel Logic Level MOSFETs are produced using ON Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.

Features

- 7.5 A, 30 V. $R_{DS(ON)} = 13 \text{ m}\Omega @ V_{GS} = 10 \text{ V}$
 $R_{DS(ON)} = 17 \text{ m}\Omega @ V_{GS} = 4.5 \text{ V}$
- Fast switching speed
- Low gate charge
- High performance trench technology for extremely low $R_{DS(ON)}$
- High power and current handling capability



Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V _{DSS}	Drain-Source Voltage	30	V
V _{GSS}	Gate-Source Voltage	± 20	V
I _D	Drain Current – Continuous (Note 1a) – Pulsed	7.5	A
		20	
P _D	Power Dissipation for Single Operation (Note 1a) (Note 1b) (Note 1c)	1.6	W
		1.0	
		0.9	
T _J , T _{STG}	Operating and Storage Junction Temperature Range	–55 to +150	°C

Thermal Characteristics

R _{θJA}	Thermal Resistance, Junction-to-Ambient (Note 1a)	78	°C/W
R _{θJC}	Thermal Resistance, Junction-to-Case (Note 1)	40	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDS6910	FDS6910	13"	12mm	2500 units

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

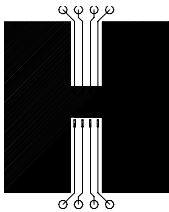
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain–Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\ \mu\text{A}$, Referenced to 25°C		28		mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}$ $V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}, T_J = 55^\circ\text{C}$			1 10	μA
I_{GSS}	Gate–Source Leakage	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$			± 100	nA
On Characteristics (Note 2)						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	1	1.8	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250\ \mu\text{A}$, Referenced to 25°C		-4.7		mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain–Source On–Resistance	$V_{GS} = 10\text{ V}, I_D = 7.5\text{ A}$ $V_{GS} = 4.5\text{ V}, I_D = 6.5\text{ A}$ $V_{GS} = 10\text{ V}, I_D = 7.5\text{ A}, T_J = 125^\circ\text{C}$		10.6 13 14.5	13 17 20	m Ω
$I_{D(on)}$	On–State Drain Current	$V_{GS} = 10\text{ V}, V_{DS} = 5\text{ V}$	20			A
g_{FS}	Forward Transconductance	$V_{DS} = 5\text{ V}, I_D = 7.5\text{ A}$		36		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = 15\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$		1130		pF
C_{oss}	Output Capacitance			300		pF
C_{rss}	Reverse Transfer Capacitance			100		pF
R_G	Gate Resistance	$V_{GS} = 15\text{ mV}, f = 1.0\text{ MHz}$		2.4		Ω
Switching Characteristics (Note 2)						
$t_{d(on)}$	Turn–On Delay Time	$V_{DD} = 15\text{ V}, I_D = 1\text{ A},$ $V_{GS} = 10\text{ V}, R_{GEN} = 6\ \Omega$		9	18	ns
t_r	Turn–On Rise Time			5	10	ns
$t_{d(off)}$	Turn–Off Delay Time			26	42	ns
t_f	Turn–Off Fall Time			7	14	ns
$Q_{g(TOT)}$	Total Gate Charge at $V_{GS}=10\text{V}$			17	24	nC
Q_g	Total Gate Charge at $V_{GS}=5\text{V}$	$V_{DD} = 15\text{ V}, I_D = 7.5\text{ A},$		9	13	nC
Q_{gs}	Gate–Source Charge			3.1		nC
Q_{gd}	Gate–Drain Charge			2.7		nC

Electrical Characteristics **TA = 25°C unless otherwise noted**

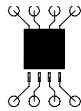
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Drain–Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain–Source Diode Forward Current				1.3	A
V_{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 1.3\text{ A}$ (Note 2)			1.2	V
t_{rr}	Diode Reverse Recovery Time	$I_F = 7.5\text{ A}, dI_F/dt = 100\text{ A}/\mu\text{s}$		24		nS
Q_{rr}	Diode Reverse Recovery Charge			13		nC

Notes:

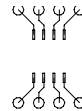
1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 78°C/W when mounted on a 0.5in² pad of 2 oz copper



b) 125°C/W when mounted on a 0.02 in² pad of 2 oz copper



c) 135°C/W when mounted on a minimum mounting pad.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300μs, Duty Cycle < 2.0%

Typical Characteristics

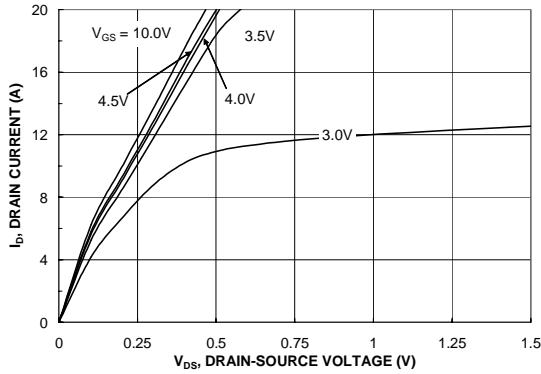


Figure 1. On-Region Characteristics.

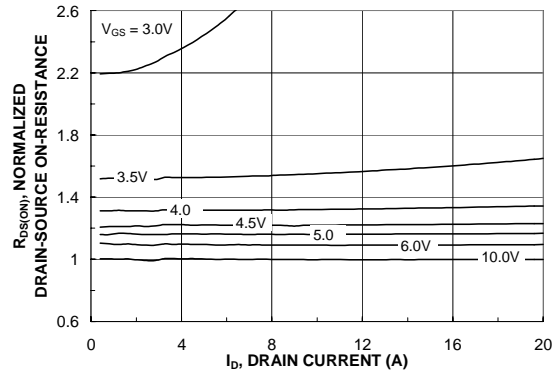


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

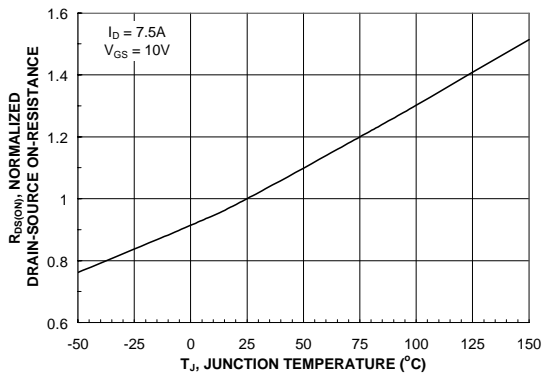


Figure 3. On-Resistance Variation with Temperature.

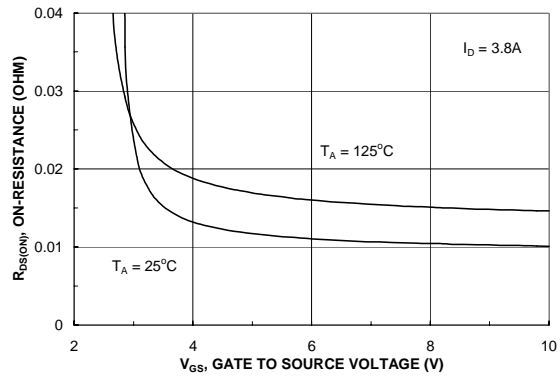


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

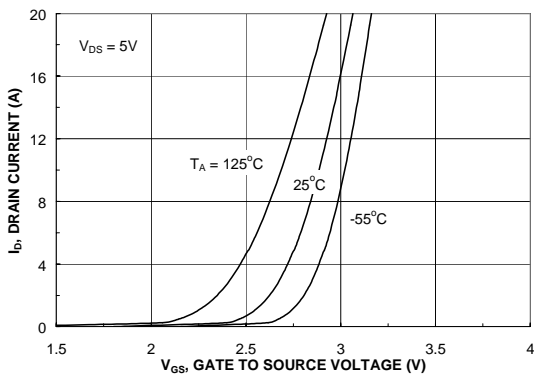


Figure 5. Transfer Characteristics.

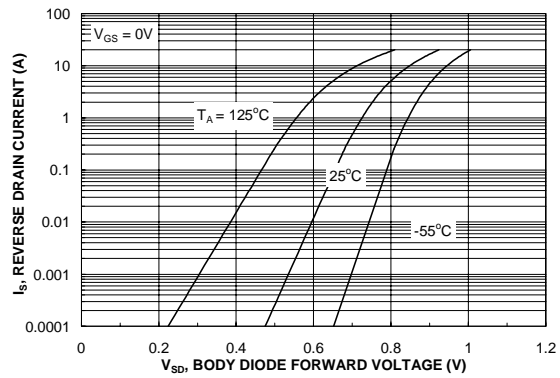


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics

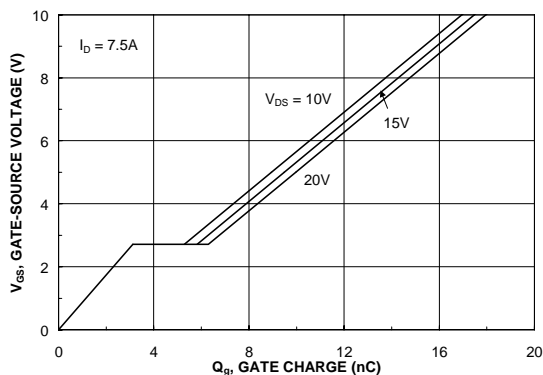


Figure 7. Gate Charge Characteristics.

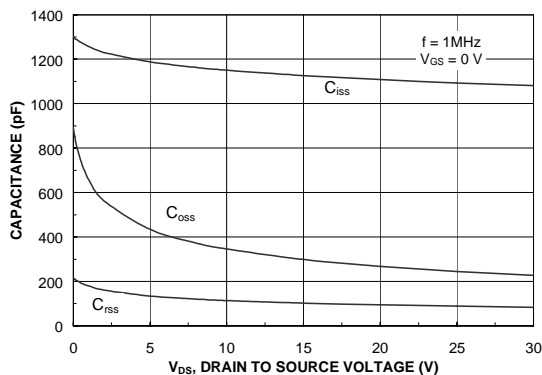


Figure 8. Capacitance Characteristics.

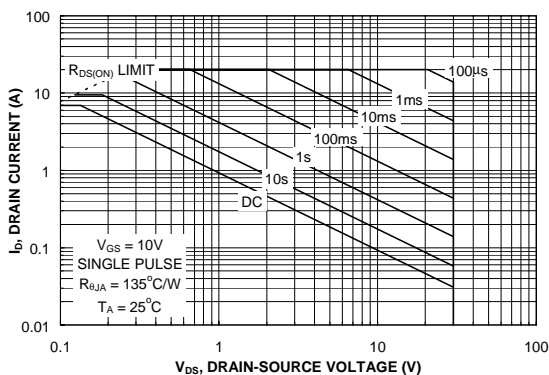


Figure 9. Maximum Safe Operating Area.

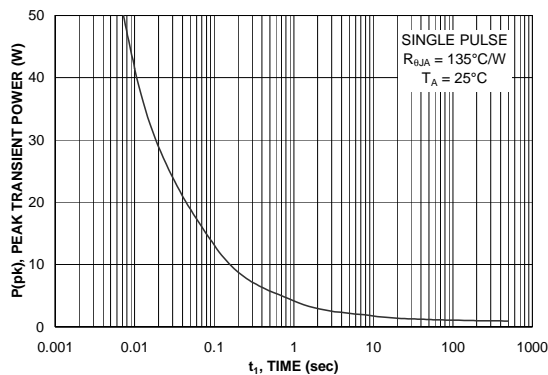


Figure 10. Single Pulse Maximum Power Dissipation.

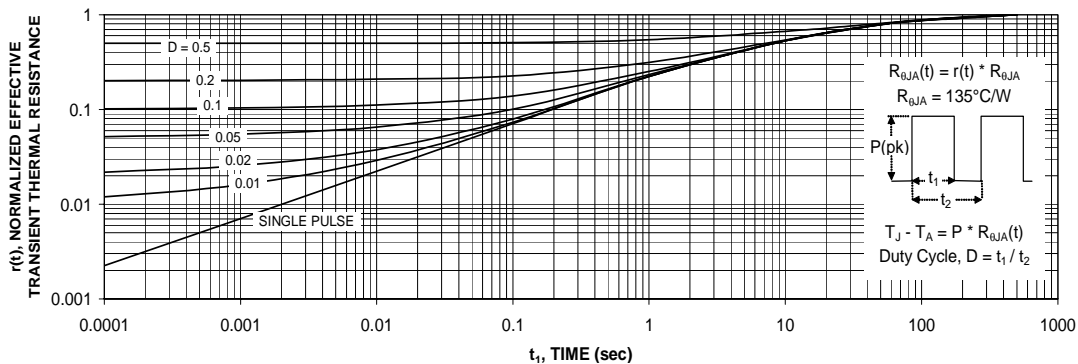



Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

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